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<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (use as many sheets as necessary)		<b>Complete if Known</b>			
		Application Number	09/922,973 - 1445		
		Filing Date	August 6, 2001		
		First Named Inventor	Theodore M. Bloomstein et al		
		Art Unit	4752 1756		
		Examiner Name	Not Yet Assigned SAGAR		
Sheet	1	of	2	Attorney Docket Number	101328-160

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. <sup>1</sup>	Document Number Number-Kind Code <sup>2</sup> (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
W	A	4,575,330	03/11/1986	Hull	425/174

FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No. <sup>1</sup>	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T <sup>6</sup>
		Country Code <sup>3</sup> -Number <sup>4</sup> -Kind Code <sup>5</sup> (if known)				

<sup>1</sup> Applicant's unique citation designation number (optional). <sup>2</sup> See attached Kinds Codes of USPTO Patent Documents at [www.uspto.gov](http://www.uspto.gov) or MPEP 901.04. <sup>3</sup> Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). <sup>4</sup> For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the application number of the patent document. <sup>5</sup> Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup> Applicant is to place a check mark here if English language Translation is attached.

OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS						
Examiner Initials	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc), date, page(s), volume-issue number(s), publisher, city and/or country where published				T <sup>2</sup>
W	B	J.M. MORAN AND D. MAYDAN, "High Resolution, Steep Profile Resist Patterns," <i>J. Vac. Sci. Technol.</i> 16(6):1620-1624(1979).				
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				Application Number	09/922,973 - 1445
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				Group Art Unit	1752 → 1757
				Examiner Name	Not Yet Assigned SAC/MT
				Attorney Docket Number	101328-160
Sheet	2	of	2		

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AG	KILIE A . ROBERT, MICHAEL B. THOMPSON "Finer Features for Functional Microdevices," <i>Nature Vol. 412:</i> 697-698(2001)

Examiner Signature

*[Signature]*

Date Considered

7/1/03.

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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